

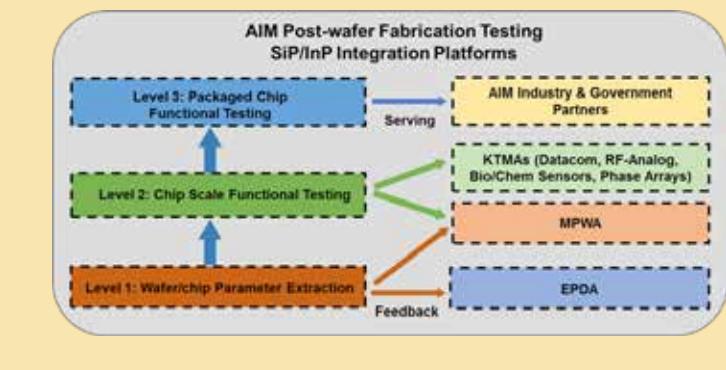
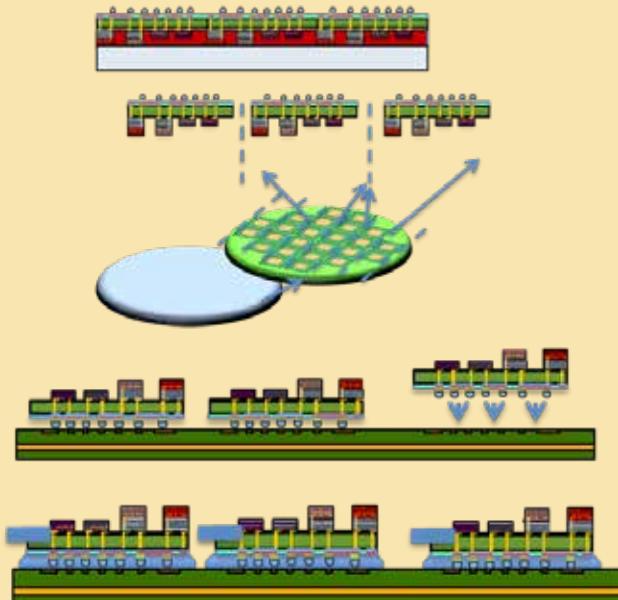


Test Assembly and Packaging Facility (TAP)

The American Institute for Manufacturing Integrated Photonics TAP facility is the world's first open 300mm State-Of-The-Art advanced ecosystem for integrated silicon photonics test, assembly, and packaging. The TAP facility is a key component in AIM Photonics' end- to-end advanced manufacturing capability for photonic integrated circuits (PIC). The facility will have development and production process capability in key areas including wafer scale, chip scale and I/O attach. In addition the facility will have State-Of-The-Art Test and Metrology capability for each of these key functional areas.

Benefits of AIM Photonics TAP Facility

- 300mm wafer compatibility
- Die attach for 2.5D and 3.0D packaging
- Automated fiber attach
- High speed automated Electro-optical testing
- Metrology for process capability evaluation
- MPW Compatibility
- Custom wafer compatibility



The TAP Facility is located at Eastman Business Park (EBP) in the ON Semiconductor facility known as building 81. ON Semiconductor will lease space which will include cleanroom, lab and office space for the TAP facility. The selected site is on Lake Avenue across from the Kodak Research Laboratory in Rochester, NY.